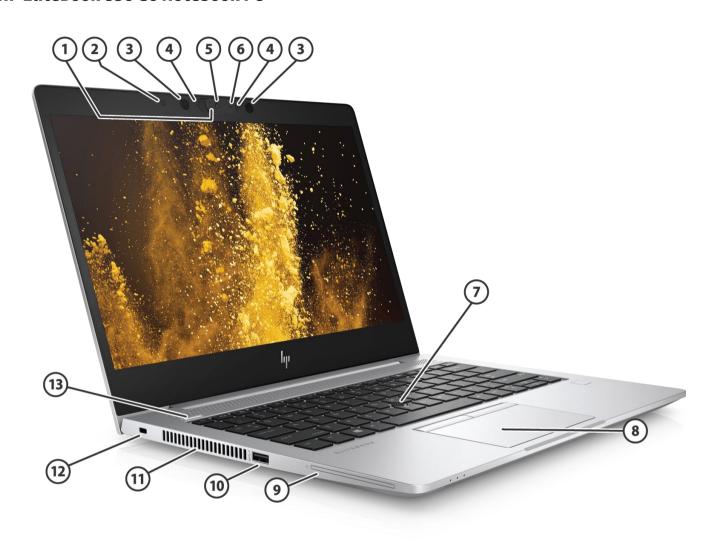
### **Overview**

### **HP EliteBook 830 G6 Notebook PC**



#### Left

- 1. HD and IR Camera (Optional)
- 2. Ambient Light Sensor (Optional)
- 3. IR Camera LEDs (Optional)
- 4. Internal Microphones
- 5. Camera Shutter
- HD Camera LED
- 7. Pointstick

- 8. Glass Clickpad
- 9. Smartcard Reader (Optional)
- 10. USB 3.1 Gen 1 Charging Port
- 11. Vents
- 12. Standard Security Lock Slot (Lock sold separately)
- 13. Power Button



### **Overview**



#### Right

- 1. Power Connector
- 2. USB Type-C™ with Thunderbolt™
- 3. Docking Connector
- 4. Ethernet Port
- 5. HDMI Port (Cable not included)

- 6. USB 3.1 Gen 1 Port
- 7. Audio Combo Jack
- 8. SIM Card Slot1
- 9. Touch Fingerprint Sensor (Optional)

1. All units have a SIM card stray but units that do not support WWAN are shipped with a non-removable SIM slot plug



#### Overview

### At a Glance

- Eye-catching Ultraslim design, premium precision-crafted machined aluminum (CNC) chassis for clean, crisp, premium look and feel
- 8th Generation Intel® Core™ i5, i7 Processors
- Preinstalled with Windows 10 versions or FreeDOS
- Designed to support all HP docking options including HP's traditional Ultraslim mechanical dock and all-new Thunderbolt dock<sup>2</sup>
- Featuring HP Collaboration Keyboard with Clickpad to manage most commonly used conferencing functions with a single keystroke
- Innovative world-facing third mic improves inbound ambient noise cancellation while 360 degree mic pick-up allows everyone to clearly hear and be heard
- Optional ultrabright displays with ambient light sensor
- Choice of displays:
  - 33.8 cm (13.3") diagonal FHD IPS Anti-Glare LED-backlit non-touch, 250 nits, 45% NTSC
  - 33.8 cm (13.3") diagonal FHD IPS Anti-Glare LED-backlit non-touch, 400 nits, 72% NTSC
  - 33.8 cm (13.3") diagonal FHD IPS Anti-Glare LED-backlit non-touch, 1000 nits, 72% NTSC with HP Sure View (Available 3Q 2019)
  - 33.8 cm (13.3") diagonal FHD IPS Anti-Glare On-Cell LED-backlit touch, 250 nits, 45% NTSC
  - 33.8 cm (13.3") diagonal FHD IPS Anti-Glare On-Cell LED-backlit touch, 1000 nits, 72% NTSC with HP Sure View (Available 3Q 2019)
- Enterprise grade security with HP Sure Sense<sup>5</sup>, HP SureStart Gen5, HP Privacy Camera, HP Sure View Gen3<sup>1</sup>, HP Sure Run Gen2, HP Sure Recover Gen2 with Embedded Reimaging<sup>2</sup>, HP Sure Click, SmartCard Reader<sup>2</sup> and Touch Fingerprint reader<sup>2</sup>
- Ultimate connectivity with optional CAT16 4G/LTE WWAN, and Thunderbolt™ Docking (dock sold separately)
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles<sup>3</sup>
- Flexible wireless connectivity options
- Choice of solid state drives up to 2 TB and DDR4 memory up to 32 GB
- Passed 19 MIL-STD 810G tests<sup>4</sup>
- UMA graphics: Up to 19 hours (Intel® 8th generation CPU and 3-cell 50 WHr battery)
- 1. HP Sure View Gen3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.
- 2. Sold separately or as an optional feature
- 3. Recharges your battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.
- 4. MIL STD 810G testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.
- 5. HP Sure Sense requires Windows 10. See product specifications for availability.

**NOTE:** See important legal disclosures for all listed specs in their respective features sections.



### **Technical Specifications**

#### **PRODUCT NAME**

HP EliteBook 830 G6 Notebook PC

#### OPERATING SYSTEMS

**Preinstalled** Windows 10 Pro 64 – HP recommends Windows 10 Pro<sup>1</sup>

Windows 10 Pro 64 (National Academic License)2

Windows 10 Home 641

Windows 10 Home Single Language 641

Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement)<sup>1</sup>

**FreeDOS** 

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

#### **PROCESSORS**

Intel® Core™ i7-8665U with Intel® UHD Graphics 620 (1.9 GHz base frequency, up to 4.8 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores) 3,4,5,6

Intel® Core™ i7-8565U with Intel® UHD Graphics 620 (1.8 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)<sup>3,4,5,6</sup>

Intel® Core™ i5-8365U with Intel® UHD Graphics 620 (1.6 GHz base frequency, up to 4.1 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores) 3,4,5,6

Intel® Core™ i5-8265U with Intel® UHD Graphics 620 (1.6 GHz base frequency, up to 3.9 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores)<sup>3,4,5,6</sup>

Intel® Core™ i3-8145U with Intel® UHD Graphics 620 (2.1 GHz base frequency, up to 3.9 GHz with Intel® Turbo Boost Technology, 4 MB L3 cache, 2 cores)<sup>3,4,5,6</sup>

#### **Processor Family**

8th Generation Intel® Core™ i7 processor (i7-8665U and i7-8565U)<sup>6</sup>

8th Generation Intel® Core™ i5 processor (i5-8365U and i5-8265U)6

8th Generation Intel® Core™ i3 processor (i3-8145U)6



### **Technical Specifications**

- 3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See <a href="http://www.intel.com/technology/turboboost">http://www.intel.com/technology/turboboost</a> for more information.
- 6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on <a href="http://www.support.hp.com">http://www.support.hp.com</a>.

#### **CHIPSET**

Chipset is integrated with processor

#### **GRAPHICS**

#### Integrated

Intel® UHD Graphics 6207

#### **Supports**

Support HD decode, DX12, HDMI 1.4b8

- 7. HD content required to view HD images.
- 8. HDMI cable sold separately.

#### **DISPLAY**

#### Non-Touch

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC (1920 x 1080)<sup>7,9,10</sup>

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim for HD camera, 250 nits, 45% NTSC (1920 x 1080)<sup>7,9,10</sup>

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim for HD+IR camera, 250 nits, 45% NTSC (1920 x 1080)  $^{7.9.10}$ 

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim for WWAN, 250 nits, 45% NTSC (1920 x 1080) <sup>7,9,10</sup>

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim for HD camera and WWAN, 250 nits, 45% NTSC (1920  $\times$  1080)  $^{7.9,10}$ 

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare LED-backlit slim for HD+IR camera and WWAN, 250 nits, 45% NTSC (1920 x 1080) 7,9,10

33.8 cm (13.3") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit ultraslim with Ambient Light Sensor for HD+IR camera, 400 nits, 72% NTSC (1920 x 1080)  $^{7,9,10}$ 

33.8 cm (13.3") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit ultraslim with Ambient Light Sensor for HD+IR camera and WWAN, 400 nits, 72% NTSC (1920 x 1080)  $^{7,9,10}$ 

33.8 cm (13.3") diagonal FHD IPS eDP + PSR WLED-backlit ultraslim with HP Sure View Gen3 Integrated Privacy Screen, Ambient Light Sensor for HD+IR camera and WWAN, 1000 nits, 72% NTSC (1920 x 1080) 7,9,10,11 (Available 3Q 2019)

#### Touch

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare on-cell WLED-backlit slim touch screen for HD+IR camera, 250 nits, 45% NTSC (1920 x 1080)<sup>7,9,10</sup>

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare on-cell WLED-backlit slim touch screen for HD+IR camera and WWAN, 250 nits, 45% NTSC (1920 x 1080)<sup>7,9,10</sup>



### **Technical Specifications**

33.8 cm (13.3") diagonal FHD IPS eDP + PSR anti-glare on-cell WLED-backlit ultraslim touch screen with HP Sure View Gen3 Integrated Privacy Screen, Ambient Light Sensor for HD+IR camera and WWAN, 1000 nits, 72% NTSC (1920 x 1080) 7,9,10,11 (Available 30 2019)

#### **HDMI 1.4b**

Supports resolution up to 4k @ 60Hz via DP and @ 30Hz via HDMI

#### **Displays support**

Supports 3 independent displays if used with optional HP UltraSlim Docking Station.2

- 7. HD content required to view HD images.
- 9. Sold separately or as an optional feature.
- 10. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 11. HP Sure View Gen3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

Docking station model	Total number of supported displays (incl. the notebook) display)	Max. resolutions supported	Dock Connectors	Technical limitations
HP UltraSlim Docking Station (Quest)	3	Dual 2.5K @ 60Hz	2xDP, 1xVGA	Dual 2.5k only with both displays intoDP
HP Thunderbolt Dock G2	3	Dual 4K @ 60Hz	TXUSB-C att-mode	Dual 4k (4096 x 2160) only with: • 1 DP + TB port or • USB-C alt mode + TB port  Dual 4K (3840 x 2160) with any of the DP, TB or USB-C alt mode video ports
HP Elite USB-C Dock G4	3	Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock	3	Dual 4K @ 60Hz Single 5K @ 60Hz	2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time

#### STORAGE AND DRIVES

**Primary Storage** 128 GB SATA-3 SS TLC<sup>12</sup>



### **Technical Specifications**

256 GB PCIe NVMe Value SS TLC<sup>12</sup>
256 GB PCIe Gen3x4 NVMe SS TLC<sup>12</sup>
256 GB SATA-3 SS TLC Opal 2<sup>12</sup>
512 GB PCIe NVMe Value<sup>12</sup>
512 GB PCIe Gen3x4 NVMe SS TLC<sup>12</sup>
512 GB Intel® PCIe® NVMe™ QLC + 32 GB Intel® Optane™ (Memory Planned to be available Q3 2019)<sup>12</sup>
512 GB PCIe Gen3x4 NVMe SS TLC Opal 2<sup>12</sup>
512 GB SATA-3 SS TLC FIPS-140-2<sup>12</sup>
1 TB PCIe Gen3x4 NVMe SS TLC<sup>12</sup>
2 TB PCIe Gen3x4 NVMe SS TLC<sup>12</sup>

12. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

#### **MEMORY**

#### **Maximum Memory**

32 GB DDR4-2400 SDRAM13

#### Memory

32 GB DDR4-2400 SDRAM (2 X 16 GB)<sup>13</sup>
16 GB DDR4-2400 SDRAM (1 X 16 GB)<sup>13</sup>
16 GB DDR4-2400 SDRAM (2 X 8 GB)<sup>13</sup>
8 GB DDR4-2400 SDRAM (1 x 8 GB)<sup>13</sup>
8 GB DDR4-2400 SDRAM (2 x 4 GB)<sup>13</sup>
4 GB DDR4-2400 SDRAM (1 x 4 GB)<sup>13</sup>

#### **Memory Slots**

2 SODIMM Both slots are customer accessible / upgradeable DDR4 SODIMMS, system runs at 2400 Supports Dual Channel Memory

13. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.



### **Technical Specifications**

#### **NETWORKING/COMMUNICATIONS**

#### WLAN

Intel® Dual Band Wireless-AC 9560 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5 Combo, vPro™<sup>14</sup> Intel® Dual Band Wireless-AC 9560 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5 Combo, non-vPro™<sup>14</sup> Intel® Wi-Fi 6 AX200 802.11a/b/g/n/ac/ax (2x2) and Bluetooth® 5 Combo, vPro™<sup>15</sup> Intel® Wi-Fi 6 AX200 802.11a/b/g/n/ac/ax (2x2) Bluetooth® 5 Combo, non-vPro™<sup>15</sup>

#### **WWAN**

Intel® XMM™ 7360 LTE-Advanced Cat 9<sup>16</sup>
Intel® XMM™ 7560 LTE-Advanced Pro Cat 16<sup>17</sup>
Intel® XMM™ 7262 LTE-Advanced Cat 6<sup>16</sup>

#### NFC

NPC300 Near Field Communication module

#### Miracast

Native Miracast Support18

#### Ethernet

Intel® I219-LM 10/100/1000 GbE, vPro™19
Intel® I219-V 10/100/1000 GbE, non-vPro™19

- 14. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.
- 15. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices.
- 16. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.
- 17. Gigabit class Category 16 4G LTE module is optional and must be configured at the factory. Module designed for up to 1 Gbps download speeds as carriers deploy 5 carrier aggregation and 100Mhz channel bandwidth, requires activation and separately purchased service contract. Backwards compatible to HSPA 3G technologies. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.
- 18. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
- 19. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.



### **Technical Specifications**

#### AUDIO/MULTIMEDIA

#### Audio

Audio by Bang & Olufsen 2 Integrated stereo speakers Integrated 3 Multi Array Microphone

#### Camera

720p HD camera<sup>7,9</sup> 720p HD IR camera<sup>7,9</sup>

#### **Sensors**

Ambient light sensor (Select models only)

- 7. HD content required to view HD images.
- 9. Sold separately or as an optional feature.

#### **KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS**

#### Keyboard

HP Premium Collaboration Keyboard, backlit and spill resistant with drain Backlit keyboard available as an option

#### **Pointing Device**

Clickpad with multi-touch gestures enabled, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

#### **Function Keys**

- F1 Display Switching
- F2 Blank or Privacy
- F3 Brightness Down
- F4 Brightness Up
- F5 Audio Mute
- F6 Volume Down
- F7 Volume Up
- F8 Mic Mute
- F9 Blank or Backlit Toggle
- F10 numlk
- F11 Wireless
- F12 Calendar
- Share/Present
- Call Answer
- Call End

#### **Hidden Function Keys**

- Fn+R Break
- Fn+S Sys Rq
- Fn+C Scroll Lock
- Fn+E Insert
- Fn+W Pause



**Technical Specifications** 



### **Technical Specifications**

#### **SOFTWARE AND SECURITY**

#### **Preinstalled Software**

Pre-boot Authentication

#### BIOS

HP BIOSphere Gen5<sup>20</sup> HP Drive Lock & Automatic Drive Lock<sup>21</sup> **BIOS Update via Network** Master Boot Record Security Power On Authentication Secure Erase<sup>22</sup> Absolute Persistence Module<sup>23</sup>

#### Software

HP Native Miracast Support<sup>24</sup> **HP Connection Optimizer HP Image Assistant HP Hotkey Support** HP JumpStart HP Support Assistant<sup>25</sup> **HP Noise Cancellation Software** Buy Office (sold separately)

#### **Manageability Features**

HP Driver Packs<sup>26</sup> HP System Software Manager (SSM) HP BIOS Config Utility (BCU) **HP Client Catalog** HP Manageability Integration Kit Gen3<sup>27</sup> Ivanti Management Suite HP Cloud Recovery<sup>28</sup>

#### **Client Security Software**

HP Client Security Manager Gen529 HP Fingerprint Sensor30 **HP Power On Authentication** Windows Defender<sup>31</sup>

**Security Management** Pre-boot Authentication TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified) SATA 0.1 port disablement (via BIOS)

Serial, USB enable/disable (via BIOS)

Power-on password (via BIOS)

Setup password (via BIOS)

Support for chassis padlocks and cable lock devices

HP Sure Click<sup>32</sup>

HP Sure Start Gen5<sup>33</sup>

HP Sure Run Gen234

HP Sure Recover Gen2<sup>35</sup>

HP Sure Sense<sup>36</sup>

#### **TPM**

Model: Infineon SLB9670



### **Technical Specifications**

Version: 7.85 Revision: TPM 2.0

FIPS 140-2 Compliant: Yes

**Smartcard Reader** 

Model number: Alcor AU9560 FIPS 201 Compliant: Yes

#### **IPv6 Certification:**

Yes

MD5 Hash: Please follow the instructions below to access MD5 Hash.

Log-on to <a href="http://hp.com/support">http://hp.com/support</a>, enter your product name, select software and drivers, select OS, select driver. After selecting the driver, click on "Associated files" and then click on "Download". When opening the file, under "Purpose" you should see the appropriate "SOFTPAQ MD5:" Field

Graphics (Intel Video Driver): TBD

WWAN: TBD WLAN: TBD

#### Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?:

Yes

UEFI version: 2.6

- 20. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.
- 21. HP Automatic Drive Lock is not supported on NVMe drives.
- 22. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- 23. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:
- http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- 24. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
- 25. HP Support Assistant requires Windows and Internet access.
- 26. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 27. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- 28. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630
- 29. HP Client Security Manager Gen5 requires Windows and is available on the select HP Pro and Elite PCs. See product specifications for details.
- 30. HP Fingerprint Sensor sold separately or as an optional feature.
- 31. Windows Defender Opt in and internet connection required for updates.



### **Technical Specifications**

- 32. HP Sure Click is available on select HP platforms and supports Microsoft Internet Explorer, Google Chrome™, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.
- 33. HP Sure Start Gen5 is available on select HP PCs with Intel processors. See product specifications for availability.
- 34. HP Sure Run Gen2: See product specifications for availability.
- 35. HP Sure Recover Gen2: See product specifications for availability. Requires an open, wired network connection. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel® Optane™.
- 36. HP Sure Sense requires Windows 10. See product specifications for availability.

#### **POWER**

#### **Power Supply**

HP Smart 45 W External AC power adapter<sup>37</sup>
HP Smart 45 W External AC power adapter, 2-prong (Japan only)<sup>37</sup>
HP Smart 65 W External AC power adapter<sup>37</sup>
HP Smart 65 W EM External AC power adapter<sup>37</sup>
45 W USB Type-C™ adapter<sup>37</sup>
65 W USB Type-C™ adapter<sup>37</sup>

#### **Primary Battery**

HP Long Life 3-cell, 50 Wh Li-ion<sup>38</sup>

#### **Battery Life**

UMA graphics: Up to 19 hours (Intel® 8th generation CPU and 3-cell 50 WHr battery)39

#### **Power Cord**

2-wire plug - 1m<sup>37</sup>
3-wire plug - 1m<sup>37</sup>
3-wire plug - 1.8m<sup>37</sup>
Duckhead power cord - 1.0m<sup>37</sup>
Duckhead power cord - 1.8m<sup>37</sup>

#### **Battery Weight**

193 +/- 10q

- 37. Availability may vary by country.
- 38. Battery is internal and not replaceable by customer. Serviceable by warranty.
- 39. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See <a href="http://www.bapco.com">http://www.bapco.com</a> for additional details



### **Technical Specifications**

#### **WEIGHTS & DIMENSIONS**

#### **Product Weight**

Starting at 2.94 lb (non-touch); Starting at 3.18 lb (touch)<sup>40</sup> Starting at 1.33 kg (non-touch); Starting at 1.44 kg (touch)<sup>40</sup>

#### Product Dimensions (W x D x H)

Non-Touch

12.22 x 9.03 x 0.7 in 31.04 x 22.93 x 1.77 cm

#### Touch

12.22 x 9.03 x 0.7 in 31.04 x 22.93 x 1.78 cm

40. Weight will vary by configuration.

#### PORTS/SLOTS

1 Thunderbolt™ (USB Type-C™ connector)

2 USB 3.1 Gen 1 (1 charging)

1 docking connector

1 HDMI 1.48

1 RJ-45

1 AC power

1 Headphone/microphone combo jack

1 SIM card slot<sup>41</sup>

1 Smartcard reader (Optional)

Standard Security Lock Slot (Lock sold separately)

#### 8. HDMI cable sold separately.

41. All units have a SIM card slot and icon but units that do not support WWAN are shipped with a non-removable SIM slot plug

#### **SERVICE AND SUPPORT**

HP Services offers 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to <a href="http://www.hp.com/support/batterywarranty">http://www.hp.com/support/batterywarranty</a>/ for additional battery information. Onsite service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: <a href="http://www.hp.com/go/cpc.42">http://www.hp.com/go/cpc.42</a>

42. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit <a href="http://www.hp.com/go/cpc">http://www.hp.com/go/cpc</a>. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



**Planned Industry Standard** 

Certifications

### **Technical Specifications**

#### **SYSTEM UNIT**

Stand-Alone Power **Nominal Operating** 19 V

**Requirements (AC Power)** Voltage

> **Average Operating Power** Win10 Integrated Graphics 6.78W **Max Operating Power UMA < 45W**

32° to 95° F (0° to 35° C) **Temperature Operating** 

> **Non-operating** -4° to 140° F (-20° to 60° C)

**Relative Humidity** Operating 10% to 90%, non-condensing

> Non-operating 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock Operating 40 G, 2 ms, half-sine

> Non-operating 200 G, 2 ms, half-sine

**Random Vibration Operating** 0.75 grms

**Non-operating** 1.50 grms

Altitude (unpressurized) **Operating** -50 to 10,000 ft (-15.24 to 3,048 m)

> -50 to 40,000 ft (-15.24 to 12,192 m) Non-operating

UL Yes **CSA** Yes **FCC Compliance** Yes

**ENERGY STAR® qualified** Select models<sup>43</sup> **EPEAT® 2019** Yes, Silver in U.S.44

**ICES** Yes **Australia** Yes **NZ A-Tick Compliance** Yes CCC Yes **Japan VCCI Compliance** Yes KC Yes **BSMI** Yes **CE Marking Compliance** Yes **BNCI or BELUS** Yes CIT Yes **GOST** Yes Saudi Arabian Compliance Yes (ICCP)

**SABS** Yes



<sup>43.</sup> Configurations of the HP Elitebook 830 G6 that are ENERGY STAR® certified are identified as HP Elitebook 830 G6 ENERGY STAR on HP websites and on http://www.energystar.gov.

<sup>44.</sup> Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.

### **Technical Specifications**

#### FNVIRONMFNTAI & INDIISTRY

ENVIRONMENT	TAL & INDUSTRY					
Environmental Data	Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:  IT ECO declaration US ENERGY STAR® US Federal Energy Management Program (FEMP) Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information. TCO 8.0 China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label*				
	System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".				
	Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 5	50Hz 100VAC, 50Hz		
	Normal Operation (Short idle)	5.04 W	4.88 W			
	Normal Operation (Long idle)	3.70 W	3.37 W	3.40 W		
	Sleep	0.90 W	0.89 W	V 0.91 W		
	Off	0.37 W	0.36 W		-	
		Note: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.				
	Heat Dissipation*	115VAC, 60Hz	230VAC, 5			
	Normal Operation (Short idle)	17 BTU/hr	16 BTU/			
	Normal Operation (Long idle)	12 BTU/hr	11 BTU/			
	Sleep	3 BTU/hr	3 BTU/h			
	Off	1 BTU/hr 1 BTU/hr 1 BTU/hr  *NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.				
	Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L <sub>WAd</sub> , bels)		Sound Pressure (L <sub>pAm</sub> , decibels)		



### **Technical Specifications**

	ypically Configured — dle		2.5	14.5	
F	ixed Disk – Random vrites		2.7	17.6	
C	Optical Drive – Sequential eads		3.4	27.7	
l	ongevity and Upgrading	years. Upgrainclude:  • 3 USB ports  • 1 PC card sl  • 1 ExpressCo  • 1 IEEE 1394  • 2 SODIMM r  • Optional ex  • 1 multi-bay  • Interchange	adeable features and/or co lot (type I/II) ard/54 slot 4 Port memory slots pansion base docking stati I I storage port eable HDD	extending its useful life by seve mponents contained in the proc ion	luct may
B	Batteries	This battery( Batteries use	he end of production.  s) in this product comply we  ed in the product do not con  ater the 1 ppm by weight	rith EU Directive 2006/66/EC	
		Battery desc Battery type			8 cell
A	Additional Information	<ul> <li>This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.</li> <li>This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.</li> <li>This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).</li> <li>This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the Silver level, see <a href="http://www.epeat.net">http://www.epeat.net</a></li> <li>Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.</li> <li>This product contains 6.14% post-consumer recycled plastic (by wt.) according to IEEE 1680.1-2018 standard, criterion 4.2.1.1.</li> <li>This product is 96.0% recycle-able when properly disposed of at end life.</li> </ul>		al and tate of 1986). Indard at marked by wt.)	
P	ackaging Materials	External:	PAPER/Corrugated		261 g
		Internal:	PLASTIC/EPE (Expanded	Polyethylene)	63 g
			PLASTIC/Polyethylene lo	ow density	14 g
			PLASTIC/PP		3 g
		The corruga		s at least 50% recycled content rials contains at least 75% recy	
		content.			



### **Technical Specifications**

RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.  We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.  We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.  To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at <a href="http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf">http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf</a> ):
	<ul> <li>Asbestos</li> <li>Certain Azo Colorants</li> <li>Certain Brominated Flame Retardants – may not be used as flame retardants in plastics</li> <li>Cadmium</li> <li>Chlorinated Hydrocarbons</li> <li>Chlorinated Paraffins</li> <li>Formaldehyde</li> <li>Halogenated Diphenyl Methanes</li> <li>Lead carbonates and sulfates</li> <li>Lead and Lead compounds</li> <li>Mercuric Oxide Batteries</li> <li>Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.</li> <li>Ozone Depleting Substances</li> <li>Polybrominated Biphenyls (PBBs)</li> <li>Polybrominated Biphenyl Ethers (PBBEs)</li> <li>Polybrominated Biphenyl Oxides (PBBOs)</li> <li>Polychlorinated Biphenyl (PCB)</li> <li>Polychlorinated Terphenyls (PCT)</li> <li>Polyvinyl Chloride (PVC) – except for wires and cables, has been voluntarily removed from most applications.</li> <li>Radioactive Substances</li> <li>Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)</li> </ul>
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	<ul> <li>Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.</li> </ul>
	Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	<ul> <li>Design packaging materials for ease of disassembly.</li> </ul>



### **Technical Specifications**

	<ul> <li>Maximize the use of post-consumer recycled content materials in packaging materials.</li> </ul>
	<ul> <li>Use readily recyclable packaging materials such as paper and corrugate materials.</li> </ul>
	<ul> <li>Reduce size and weight of packages to improve transportation fuel efficiency.</li> </ul>
	<ul> <li>Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.</li> </ul>
End-of-life Management and Recycling	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to:
	http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: <a href="http://www.hp.com/go/recyclers">http://www.hp.com/go/recyclers</a> . These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporate Environmental	For more information about HP's commitment to the environment:
Information	Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp- information/environment/ecolabels.html
	ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

#### **DISPLAYS**

Panel LCD 13.3 inch
diagonal FHD (1920 x 1080)
Anti-Glare WLED UWVA 45
percent cg 250 nits eDP 1.2
w/o PSR slim
Outline Dim
Active Area
Weight
Diagonal Si:

Outline Dimensions (W x H x D) 300.56 x 187.77 mm (max) (w/ PCB & w/o bracket)

ctive Area 293.76 x 165.24 mm (typ.)

255.76 X 165.2 1 11111 (typ

Weight 260 g (max)

Diagonal Size 13.3 inch

Thickness 3.0 mm (max)
Interface eDP 1.2 (2 lane)

**Surface Treatment** Anti-Glare

**Touch Enabled** No

**Contrast Ratio** 600:1 (typ.)

Refresh Rate 60 Hz

**Brightness** 250 nits (typ.) **Pixel Resolution** 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB Backlight LED



### **Technical Specifications**

**Color Gamut Coverage** 45% of NTSC **Color Depth** 6 bits

Viewing Angle UWVA 85/85/85

Panel LCD 13.3 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45 percent cg 250 nits eDP slim On-cell Touch

**Outline Dimensions (W x H x D)** 300.56 x 187.77

**Active Area** 293.76 x 165.24 mm (typ.)

Weight 268 g (max)

Diagonal Size 13.3 inch

Thickness 3.2 mm (max)
Interface eDP 1.2

Surface Treatment Anti-Glare On-cell

**Touch Enabled** Yes

Contrast Ratio600:1 (typ.)Refresh Rate60 HzBrightness250 nits

**Pixel Resolution** 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB Backlight LED

**Color Gamut Coverage** 45% of NTSC **Color Depth** 6 bits

Viewing Angle UWVA 85/85/85

Panel LCD 13.3 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 72 percent cg 400 nits eDP 1.4+PSR2 Slim

 Outline Dimensions (W x H x D)
 299.06 x 185.54 mm (max)

 Active Area
 293.76 x 165.24 mm (typ.)

Weight170 g (max)Diagonal Size13.3 inchThickness2.0 mm (max)

Interface eDP 1.4 + PSR2 (2 lane)

Surface Treatment Anti-Glare

Touch Enabled No

Contrast Ratio1200:1 (typ.)Refresh Rate60 HzBrightness400 nits

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB Backlight LED

**Color Gamut Coverage** 72% of NTSC

Color Depth 8 bits

Viewing Angle UWVA 85/85/85



Outline Dimensions (W x H x D) 315.31 x 195.498 mm (max)

### **Technical Specifications**

Panel LCD 13.3 inch
diagonal FHD (1920 x 1080)
Anti-Glare WLED UWVA 72
percent cg 1000 nits eDP
1.4+PSR2 flat Privacy
Active A
Weight
Diagona
Thickne

**Active Area** 309.312 x 173.988 mm (typ.)

Weight 265 g (max)
Diagonal Size 13.3 inch
Thickness 3.0 mm (max)

**Interface** eDP 1.4 + PSR2 (4 lane)

Surface Treatment Anti-Glare
Touch Enabled No

Contrast Ratio2000:1 (typ.)Refresh Rate60 HzBrightness1000 nits

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB Backlight LED

**Color Gamut Coverage** 72% of NTSC

Color Depth 8 bits

Viewing Angle UWVA 85/85/85

Panel LCD 13.3 inch
diagonal FHD (1920 x 1080)
Anti-Glare WLED UWVA 72
percent cg 1000 nits
eDP+PSR flat On-cell Touch
Privacy
Outline Dimer
Active Area
Weight
Diagonal Size

 Outline Dimensions (W x H x D)
 299.06 x 186.54 mm (max)

 Active Area
 293.76 x 165.24 mm (typ.)

Weight260 g (max)Diagonal Size13.3 inchThickness3.2 mm (max)

Interface eDP 1.4 + PSR2 (4 lane)
Surface Treatment Anti-Glare On-cell

**Touch Enabled** YES

Contrast Ratio2000:1 (typ.)Refresh Rate60 HzBrightness1000 nits

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB Backlight LED

**Color Gamut Coverage** 72% of NTSC

**Color Depth** 8 bits

Viewing Angle UWVA 85/85/85



### **Technical Specifications**

#### STORAGE AND DRIVES

SSD 128 GB 2280 M2 SATA- Form Factor 3 TLC

Form Factor M.2 2280
Capacity 128 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 ATA-8, SATA 3.0

Maximum Sequential ReadAround 540 ~ 560 MB/sMaximum Sequential WriteAround 380 ~ 530 MB/s

**Logical Blocks** 250,069,680

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security; DIPM; TRIM; DEVSLP

SSD 1 TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided Form Factor M.2 2280
Capacity 1 TB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

Maximum Sequential ReadAround 3200 ~ 3480 MB/sMaximum Sequential WriteAround 2400 ~ 3037 MB/s

**Logical Blocks** 2,000,409,264

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

**Features** ATA Security; TRIM; L1.2

SSD 256 GB 2280 M2 PCIe-3x4 SS NVMe TLC Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

Maximum Sequential Read Around 2900 ~ 3167 MB/s
Maximum Sequential Write Around 1300 ~ 1663 MB/s

**Logical Blocks** 500,118,192

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

**Features** ATA Security; TRIM; L1.2



### **Technical Specifications**

SSD 256 GB 2280 M2 SATA- Form Factor
3 Self Encrypted OPAL2 Capacity
Three Layer Cell

Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 ATA-8, SATA 3.0

Maximum Sequential ReadAround 530 ~ 560 MB/sMaximum Sequential WriteAround 500 ~ 530 MB/s

**Logical Blocks** 500,118,192

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG OPAL 2.0; DIPM; TRIM; DEVSLP

SSD 256 GB 2280 PCIe NVMe Form Factor Value

Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

Maximum Sequential ReadAround 1500 ~ 1700 MB/sMaximum Sequential WriteAround 780 ~ 1300 MB/s

**Logical Blocks** 500,118,192

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2

2 TB 2280 PCIe-3x4 NVMe Three Layer Cell singlesided Form Factor M.2 2280
Capacity 2 TB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

Maximum Sequential Read Around 2900 ~ 3000 MB/s

Maximum Sequential WriteAround 2100 MB/sLogical Blocks3,907,029,168

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

**Features** ATA Security; TRIM; L1.2



### **Technical Specifications**

SSD 512 GB 2280 M2 PCIe-3x4 SS NVMe TLC Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

Maximum Sequential ReadAround 2700 ~ 3400 MB/sMaximum Sequential WriteAround 1390 ~ 2956 MB/s

**Logical Blocks** 1,000,215,215

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2

SSD 512 GB 2280 M2 SATA-3 Three Layer Cell Federal Information Processing Standard

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

Height 2.6 mm Max
Width 0.87 in (22 mm)
Weight 0.02 lb (10 g)
Interface ACS-3, SATA 3.2
Maximum Sequential Read Around 530 MB/s
Maximum Sequential Write Around 400 MB/s
Logical Blocks 1,000,215,216

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS; DIPM; TRIM; DEVSLP

SSD 512 GB 2280 PCIe NVMe Form Factor Value

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC/QLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

Maximum Sequential ReadAround 1500 ~ 1700 MB/sMaximum Sequential WriteAround 860 ~ 1500 MB/s

**Logical Blocks** 1,000,215,215

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

**Features** ATA Security: TRIM: L1.2

Form Factor M.2 2280



### **Technical Specifications**

Capacity 512 GB NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

Maximum Sequential ReadAround 2900 ~ 3400 MB/sMaximum Sequential WriteAround 1000 ~ 2500 MB/s

SSD 512 GB 2280 PCIe-3x4
NVMe Self Encrypted OPAL2

Logical Blocks 1,000,215,216
32° to 158°F (0° to 70°C) [ambient temp]

Three Layer Cell Features ATA Security; TCG Opal 2.0; FIPS; DIPM; TRIM; DEVSLP



### **Technical Specifications**

#### **NETWORKING/COMMUNICATIONS**

Intel® 9560 Wireless LAN Standards IE 802.11a/b/g/n/ac (2x2) IE Wi-Fi® and Bluetooth® 5.0

Combo<sup>1</sup> vPro

IS IEEE 802.11a IEEE 802.11b

> IEEE 802.11g IEEE 802.11n IEEE 802.11ac

Interoperability Wi-Fi® certified
Frequency Band 802.11b/g/n

•2.402 - 2.482 GHz

802.11a/n

•4.9 – 4.95 GHz (Japan) •5.15 – 5.25 GHz •5.25 – 5.35 GHz •5.47 – 5.725 GHz •5.825 – 5.850 GHz

**Data Rates** •802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz &

160MHz)

**Modulation** Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security<sup>3</sup>
•IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

•AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

•WPA2 certification •IEEE 802.11i

•Cisco Certified Extensions, all versions through CCX4 and CCX Lite

•WAPI

**Network Architecture** 

Models Roaming Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Output Power<sup>2</sup>

IEEE 802.11 compliant roaming between access points

•802.11b: +18.5dBm minimum •802.11g: +17.5dBm minimum •802.11a: +18.5dBm minimum

•802.11a: +18.5dBm minimum •802.11n HT20(2.4GHz): +15.5dBm minimum

•802.11n HT40(2.4GHz): +14.5dBm minimum •802.11n HT20(5GHz): +15.5dBm minimum •802.11n HT40(5GHz): +14.5dBm minimum •802.11ac VHT80(5GHz): +11.5dBm minimum •802.11ac VHT160(5GHz): +11.5dBm minimum

Power Consumption

•Transmit mode 2.0 W

•Receive mode 1.6 W

•Idle mode (PSP) 180 mW (WLAN Associated) •Idle mode 50 mW (WLAN unassociated)

Connected Standby 10mWRadio disabled 8 mW



### **Technical Specifications**

**Power Management** ACPI and PCI Express compliant power management

802.11 compliant power saving mode

**Receiver Sensitivity** <sup>3</sup> 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

**Antenna type** High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

**Dimensions** Type 2230: 2.3 x 22.0 x 30.0 mm

 Weight
 Type 2230: 2.8g

 Operating Voltage
 3.3v +/- 9%

**Temperature** Operating 14° to 158° F (–10° to 70° C)

Non-operating  $-40^{\circ}$  to  $176^{\circ}$  F ( $-40^{\circ}$  to  $80^{\circ}$  C)

**Humidity** Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

**Altitude** Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

**LED Activity** LED Amber – Radio OFF; LED White – Radio ON

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

#### HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

**Bluetooth Specification** 4.0/4.1/4.2/5.0 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH)

Channels BLE: 0~39 (2 MHz/CH)

**Signaling Data Rate** Legacy: 3 Mbps signaling data rate<sup>1</sup> 2.17 Mbps

BLE: 1 Mbps signaling data rate<sup>1</sup> 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

**Transmit Power** The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 4 dBm for BR and EDR.

**Power Consumption** Peak (Tx) 330 mW

Peak (Rx) 230 mW



### **Technical Specifications**

Selective Suspend 17 mW

**Electrical Interface** 

USB 2.0 compliant

Bluetooth Software Supported

-

Microsoft Windows Bluetooth Software

**Power Management** 

Microsoft Windows ACPI, and USB Bus Support

Certifications

**Link Topology** 

FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management Certifications ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode

LE Link Layer
LE Low Duty Cycle Directed Advertising

LE LOW Duty Cycle Directed Advertising
LE L2CAP Connection Oriented Channels
Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

**Security & Manageability** Intel® vPro™ support with appropriate Intel® chipset components



### **Technical Specifications**

Intel® 9560 Wireless LAN Standards 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5.0 Combo¹ non-vPro

IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac

Interoperability Wi-Fi® certified

Frequency Band 802.11b/g/n
•2.402 – 2.482 GHz

802.11a/n

•4.9 – 4.95 GHz (Japan) •5.15 – 5.25 GHz •5.25 – 5.35 GHz •5.47 – 5.725 GHz •5.825 – 5.850 GHz

**Data Rates** •802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, , 80MHz &

160MHz)

**Modulation** Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security<sup>3</sup> •IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

•AES-CCMP: 128 bit in hardware

802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

•WPA2 certification •IEEE 802.11i

•Cisco Certified Extensions, all versions through CCX4 and CCX Lite

•WAPI

Network Architecture

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

**Roaming** IEEE 802.11 compliant roaming between access points

•802.11b: +18.5dBm minimum

•802.11g: +17.5dBm minimum •802.11a: +18.5dBm minimum

•802.11n HT20(2.4GHz): +15.5dBm minimum •802.11n HT40(2.4GHz): +14.5dBm minimum •802.11n HT20(5GHz): +15.5dBm minimum •802.11n HT40(5GHz): +14.5dBm minimum •802.11ac VHT80(5GHz): +11.5dBm minimum •802.11ac VHT160(5GHz): +11.5dBm minimum

**Power Consumption** •Transmit mode 2.0 W

•Receive mode 1.6 W

•Idle mode (PSP) 180 mW (WLAN Associated)
•Idle mode 50 mW (WLAN unassociated)

Connected Standby 10mWRadio disabled 8 mW



### **Technical Specifications**

**Power Management** ACPI and PCI Express compliant power management

802.11 compliant power saving mode

**Receiver Sensitivity 3** 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

**Antenna type** High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

**Dimensions** Type 2230: 2.3 x 22.0 x 30.0 mm

 Weight
 Type 2230: 2.8g

 Operating Voltage
 3.3v +/- 9%

**Temperature** Operating 14° to 158° F (–10° to 70° C)

Non-operating  $-40^{\circ}$  to  $176^{\circ}$  F ( $-40^{\circ}$  to  $80^{\circ}$  C)

**Humidity** Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

**Altitude** Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

**LED Activity** LED Amber – Radio OFF; LED White – Radio ON

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

#### HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

**Bluetooth Specification** 4.0/4.1/4.2/5.0 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH)

Channels BLE: 0~39 (2 MHz/CH)

**Signaling Data Rate** Legacy: 3 Mbps signaling data rate<sup>1</sup> 2.17 Mbps

BLE: 1 Mbps signaling data rate<sup>1</sup> 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

**Transmit Power** The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 4 dBm for BR and EDR.

**Power Consumption** Peak (Tx) 330 mW

Peak (Rx) 230 mW



### **Technical Specifications**

Selective Suspend 17 mW

Bluetooth Software Supported Link Topology Microsoft Windows Bluetooth Software

Power Management Certifications Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management Certifications ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE  $\operatorname{\mathsf{Mark}}$ 

Bluetooth Software Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)



### **Technical Specifications**

Intel® 22260 802.11a/b/g/n/ac/ax (2x2) Wi-Fi® 6 and Bluetooth® 5.1 Combo¹ vPro Wireless LAN Standards IEEE 802.11a

IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11ax
IEEE 802.11d
IEEE 802.11d
IEEE 802.11t
IEEE 802.11h
IEEE 802.11h
IEEE 802.11t
IEEE 802.11r
IEEE 802.11r

Interoperability Frequency Band Wi-Fi® certified **802.11b/g/n** 

•2.402 - 2.482 GHz

802.11a/n

•4.9 – 4.95 GHz (Japan) •5.15 – 5.25 GHz •5.25 – 5.35 GHz •5.47 – 5.725 GHz •5.825 – 5.850 GHz

**Data Rates** 

•802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz &

160MHz)

**Modulation** Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security<sup>3</sup>

•IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

•WPA2 certification •IEEE 802.11i

Cisco Certified Extensions, all versions through CCX4 and CCX Lite

•WAPI

**Network Architecture** 

Models Roaming

Output Power<sup>2</sup>

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

IEEE 802.11 compliant roaming between access points

•802.11b: +18.5dBm minimum •802.11q: +17.5dBm minimum

•802.11a: +18.5dBm minimum

•802.11n HT20(2.4GHz): +15.5dBm minimum •802.11n HT40(2.4GHz): +14.5dBm minimum •802.11n HT20(5GHz): +15.5dBm minimum •802.11n HT40(5GHz): +14.5dBm minimum •802.11ac VHT80(5GHz): +11.5dBm minimum



### **Technical Specifications**

•802.11ac VHT160(5GHz): +11.5dBm minimum •802.11ax HT40(2.4GHz): +10dBm minimum

•802.11ax VHT160(5GHz): +10dBm minimum

**Power Consumption** •Transmit mode 2.0 W

•Receive mode 1.6 W

•Idle mode (PSP) 180 mW (WLAN Associated) •Idle mode 50 mW (WLAN unassociated)

•Connected Standby 10mW •Radio disabled 8 mW

**Power Management** ACPI and PCI Express compliant power management

802.11 compliant power saving mode

**Receiver Sensitivity <sup>3</sup>** •802.11b, 1Mbps: -93.5dBm maximum

•802.11b, 11Mbps: -84dBm maximum
• 802.11a/g, 6Mbps: -86dBm maximum
• 802.11a/g, 54Mbps: -72dBm maximum
• 802.11n, MCS07: -67dBm maximum
• 802.11n, MCS15: -64dBm maximum
• 802.11ac, MCS0: -84dBm maximum
• 802.11ac, MCS9: -59dBm maximum
• 802.11ax, MCS11(HT40): -59dBm maximum

•802.11ax, MCS11(H140): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

**Dimensions** 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

**Weight** 1. Type 2230: 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

**Temperature** Operating 14° to 158° F (–10° to 70° C)

Non-operating  $-40^{\circ}$  to  $176^{\circ}$  F ( $-40^{\circ}$  to  $80^{\circ}$  C)

**Humidity** Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

#### HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

**Bluetooth Specification** 4.0/4.1/4.2/5.0/5.1 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH)
Channels BLE: 0~39 (2 MHz/CH)



### **Technical Specifications**

**Signaling Data Rate** Legacy: 3 Mbps signaling data rate<sup>1</sup> 2.17 Mbps

BLE: 1 Mbps signaling data rate<sup>1</sup> 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

**Transmit Power** The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 4 dBm for BR and EDR.

**Power Consumption** Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Bluetooth Software Supported Link Topology Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management Certifications ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL. CSA. and CE Mark

Bluetooth Software Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

**Security & Manageability** Intel® vPro™ support with appropriate Intel® chipset components



### **Technical Specifications**

Intel® 22260 802.11a/b/g/n/ac/ax (2x2) Wi-Fi® 6 and Bluetooth® 5.1 Combo¹ non-vPro Wireless LAN Standards IEEE 802.11a

IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11d
IEEE 802.11d
IEEE 802.11e
IEEE 802.11h
IEEE 802.11h
IEEE 802.11t
IEEE 802.11r
IEEE 802.11v
Wi-Fi® certified

Interoperability Wi-Fi® certified

Frequency Band

802.11b/g/n/ax

•2.402 – 2.482 GHz

802.11a/n/ac/ax

•4.9 – 4.95 GHz (Japan)

•5.15 – 5.25 GHz

•5.25 – 5.35 GHz •5.47 – 5.725 GHz •5.825 – 5.850 GHz

**Data Rates** •802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

• 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

**Modulation** Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security<sup>3</sup> •IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

•AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

•WPA2 certification •IEEE 802.11i

Cisco Certified Extensions, all versions through CCX4 and CCX Lite

•WAPI

**Network Architecture** 

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

**Roaming** IEEE 802.11 compliant roaming between access points

•802.11b: +18.5dBm minimum

•802.11g: +17.5dBm minimum •802.11a: +18.5dBm minimum

•802.11n HT20(2.4GHz): +15.5dBm minimum •802.11n HT40(2.4GHz): +14.5dBm minimum •802.11n HT20(5GHz): +15.5dBm minimum •802.11n HT40(5GHz): +14.5dBm minimum



### **Technical Specifications**

•802.11ac VHT80(5GHz): +11.5dBm minimum •802.11ac VHT160(5GHz): +11.5dBm minimum •802.11ax HT40(2.4GHz): +10dBm minimum •802.11ax VHT160(5GHz): +10dBm minimum

**Power Consumption** •Transmit mode 2.0 W

•Receive mode 1.6 W

•Idle mode (PSP) 180 mW (WLAN Associated) •Idle mode 50 mW (WLAN unassociated)

•Connected Standby 10mW
•Radio disabled 8 mW

**Power Management** ACPI and PCI Express compliant power management

802.11 compliant power saving mode

**Receiver Sensitivity** •802.11b, 1Mbps: -93.5dBm maximum

•802.11b, 11Mbps: -84dBm maximum
• 802.11a/g, 6Mbps: -86dBm maximum
• 802.11a/g, 54Mbps: -72dBm maximum
• 802.11n, MCS07: -67dBm maximum
• 802.11n, MCS15: -64dBm maximum
• 802.11ac, MCS0: -84dBm maximum
• 802.11ac, MCS9: -59dBm maximum

•802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum

**Antenna type** High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

**Dimensions** 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

**Weight** 1. Type 2230: 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

**Temperature** Operating 14° to 158° F (–10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

**Humidity** Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

**Altitude** Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

#### HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0/5.1 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH)

Channels BLE: 0~39 (2 MHz/CH)



### **Technical Specifications**

**Signaling Data Rate** Legacy: 3 Mbps signaling data rate<sup>1</sup> to 2.17 Mbps

BLE: 1 Mbps signaling data rate<sup>1</sup> 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

**Transmit Power** The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 9.5 dBm for BR and EDR.

**Power Consumption** Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Bluetooth Software Supported Link Topology Microsoft Windows Bluetooth Software

**Power Management** Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management

Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Software Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)



### **Technical Specifications**

Intel® XMM 7360 LTE-Advanced CAT9 Technology/Operating bands

**/Uperating** FUULTI

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700 (2100 (Band 4), 250 (Band 5), 2600 (Band 7), 200

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300

(Band 30), 1700/2100 (Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band

41).

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

Wireless protocol

standards

3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up

to 450Mbps; UL 20MHz throughput up to 50Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

**GPS bands** 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098

MHz

Maximum data rates LTE: 450 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 5.8 g

Dimensions

(Length x Width x

42 x 30 x 2.3 mm

Thickness)

Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Intel® XMM 7262 LTE-Advanced CAT6

Technology/Operating

(Band 8), 800 (Band 20), 700 (Band 28),

FDD LTE: 2100 (Band 1), 1800 (Band 3), 850 (Band 5), 2600 (Band 7), 900

UCDA . . 2100 (Dana 20), 700 (Dana 20),

HSPA+: 2100 (Band 1), 850 (Band 5), 900 (Band 8)

Wireless protocol

standards

bands

3GPP Release 11 LTE Specification CAT.6, DL 40MHz BW throughput up

to 300Mbps; UL 20MHz throughput up to 50Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B and XTRA)

**GPS bands** 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

Maximum data rates LTE: 300 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) UMT: 384 kbps (Download), 384 kbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm



#### **Technical Specifications**

Maximum powerLTE: 1,200 mA (peak); 900 mA (average)consumptionHSPA+: 1,100 mA (peak); 800 mA (average)

**Form Factor** M.2, 3042-S3 Key B

Weight 6 q

**Dimensions** 

(Length x Width x 42 x 30 x 2.3 mm

Thickness)

Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Intel® XMM™ 7560 LTE-Advanced Pro **Technology/Operating** FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

bands 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700

(Band 12 lower),

700 (Band 13 upper), 700 (Band 14 upper), 700 (Band 17 lower), 850

(Band 18 lower),

850 (Band 19 upper), 800 (Band 20), 1900 (Band 25), 850 (Band 26), 700

(Band 28),

700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band

41), 3500 (Band 42), 5200 (Band 46 RX only)

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MH

Wireless protocol standards

3GPP Release 12 LTE Specification DL-CAT.16, DL 100MHz BW throughput up to 978Mbps; UL-CAT.13 40MHz throughput up to

150Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

**GPS** Standalone, A-GPS (MS-B and LTO)

**GPS bands** GPS 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou

1561.098 ± 2.046 MHz

Maximum data rates LTE: 978 Mbps (Download), 150 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm in all bands except B41

LTE B41 HPUE: 26dBm HSPA+: 23.5 dBm

Maximum power LTE: 1,200 mA (peak); 900 mA (average) consumption HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6 g

**Dimensions** 

(Length x Width x 42 x 30 x 2.3 mm

Thickness)

Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and



### **Technical Specifications**

availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Near Field Communications Controller (optional) Dimensions (L x W x H)

Module 17 mm by 10 mm by 2.0 mm

Chipset

NPC300

**12C** 

System interface NFC RF standards

ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693

ISO/IEC 18092

ECMA-340 NFCIP-1 Target and Initiator

ECMA-320 NFCIP-2

NFC Forum Support

Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2

Reader (PCD-VCD)

Mode (1)

ISO/IEC 14443 A ISO/IEC 14443 B

ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire

FeliCa

Jewel and Topaz cards

Card Emulation (PICC-VICC) Mode (1) ISO/IEC 14443 A ISO/IEC 14443 B and B'

MIFARE FeliCa

Frequency 13.56 MHz

**NFC Modes Supported** Reader/Writer, Peer-to-Peer 106, 212, 424, 848 kbps

Operating temperature -25 C to 80°C
Storage temperature -20°C to 125°C
Humidity 10-90% operating

5-95% non-operating

**Supply Operating voltage** 2.7 to 5.5 Volts **I/O Voltage** 1.8V or 3.3V

Power Consumption (Booster enable, VBAT= 3.3V, VCC\_BOOST = 5V) Mode Power Consumption, Typical

Polling710.93 mWDetected Test Tag Type 1152.09 mWDetected Test Tag Type 2341.26 mWDetected Test Tag Type 3383.76 mWDetected Test Tag Type 4312.26 mW

**Antenna** Antenna connector, 0.3mm pitch, 7 connector FPC. Antenna matching is

external to module.



### **Technical Specifications**

Intel® i219LM 10/100/1000 Integrated NIC

**Connector** RJ-45

**System Interface** PCI(Intel proprietary) + SMBus

**Data rates supported** 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)

100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-

30)

1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100

Mbit/s

IEEE Compliance IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE (Energy Efficient Ethernet)

**Performance** TCP/IP/UDP Checksum Offload (configurable)

Protocol Offload (ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling Jumbo Frame 9K

**Power consumption** Cable Disconnection: 25mW

100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW

**Power** ACPI compliant – multiple power modes

**Management** Situation-sensitive features reduce power consumption

Advanced link down power saving for reducing link down power

consumption

Management Interface Auto MDI/MDIX Crossover cable detection

IT Manageability Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft

Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB

(802.3x, clause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

**Security & Manageability** Intel® vPro™ support with appropriate Intel® chipset components

Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.



### **Technical Specifications**

Intel® i219v 10/100/1000 Integrated NIC **Connector** RJ-45

System Interface PCI(Intel proprietary) + SMBus

**Data rates supported** 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)

100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-

30)

1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100

Mbit/s

IEEE Compliance IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE (Energy Efficient Ethernet)

**Performance** TCP/IP/UDP Checksum Offload (configurable)

Protocol Offload (ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling Jumbo Frame 9K

**Power consumption** Cable Disconnection: 25mW

100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW

**Power** ACPI compliant – multiple power modes

**Management** Situation-sensitive features reduce power consumption

Advanced link down power saving for reducing link down power

consumption

Management Interface Auto MDI/MDIX Crossover cable detection

IT Manageability Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft

Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB

(802.3x, clause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.



### **Technical Specifications**

#### **POWER**

Wall Mount USB type C Straight 1.8m C6NS

AC Adapter 45 Watt nPFC Dimensions (H x W x D)

Weight Input

Output

62.0 x 62.0 x 28.5mm

unit: 220g +/- 10g **Input Efficiency** 

Average Efficiency of 25%, 50%, 75%, 100%

load condition with 115Vac/230Vac Spec:

5V: 81.5% 9V: 86.7% 10V: 87.5% 12V: 87.8% 15V: 87.8% 20V: 87.8%

Input frequency range

47 ~ 63Hz **Input AC current** 

Max. 1.4 A at 90 Vac

**Output power** Average Efficiency of 25%, 50%, 75%, 100%

load condition with 115Vac/230Vac Spec:

**DC** output 5V: 81.5% Hold-up time 9V: 86.7% **Output current limit** 10V: 87.5%

Connector Non-Standard C6

**Environmental Design** 

**Operating** temperature

32oF to 95oF (0oto 35oC)

Non-operating (storage)

-4oF to 185oF (-20oto 85oC) temperature **Altitude** 0 to 16,400 ft (0 to 5000m)

**Humidity** 20% to 95% **Storage Humidity** 10% to 95%

**EMI and Safety** Certifications

\*CE Mark - full compliance with LVD and EMC directives

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

\* MTBF - over 200,000 hours at 25°C ambient condition.



### **Technical Specifications**

AC Adapter 45 Watt Smart Dimensions (H x W x D)

nPFC Standard Barrel 4.5 mm Right Angle 1.8 m

95.0x40.0x26.5mm Weight

unit: 200g +/- 10g

Input **Input Efficiency** 87.74 % at 115 Vac and 88.4 % at 230Vac

> Input frequency range 47 ~ 63 Hz

**Input AC current** Max. 1.4 A at 90 Vac

Output **Output power** 45W

> DC output 19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <8.0A

Connector 6

**Operating Environmental Design** 32° to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4° to 185°F (-20° to 85°C)

temperature

**Altitude** 0 to 16.400 ft (0 to 5000m)

**Humidity** 20% to 95% **Storage Humidity** 10% to 95%

**EMI and Safety** Certifications

\*CE Mark - full compliance with LVD and EMC directives

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1. SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

\* MTBF - over 200.000 hours at 25°C ambient condition.

AC Adapter 45 Watt Smart Dimensions (H x W x D) nPFC Standard Barrel 4.5 mm Right Angle 1.8 m 2prong

95.0 x 40.0 x 26.5mm

Weight Input

unit: 200g +/- 10g **Input Efficiency** 

87.74 % at 115 Vac and 88.4 % at 230Vac

Input frequency range 47 ~ 63 Hz

**Input AC current** Max. 1.4 A at 90 Vac

Output **Output power** 45W

> DC output 19.5V

Hold-up time 5ms at 115 Vac input

**Output current limit** <8.0A

Connector

**Environmental Design Operating** 32° to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4° to 185°F (-20° to 85°C)

temperature

Altitude

0 to 16,400 ft (0 to 5000m)



### **Technical Specifications**

Humidity 20% to 95% Storage Humidity 10% to 95%

EMI and Safety Certifications

Input

\*CE Mark - full compliance with LVD and EMC directives

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV: Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B.

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

\* MTBF - over 200.000 hours at 25°C ambient condition.

AC Adapter 65 Watt nPFC Dimensions (H x W x D)
USB type C Straight 1.8m
Weight
C6NS

**Dimensions (H x W x D)** 74 x 74 x 28.5 mm

**Weight** unit: 245g +/- 10g

Input Efficiency 81.5% min at 115 Vac/ 230Vac @ 5V/3A

86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

**Input frequency range** 47 to 63 Hz

**Input AC current** 1.7 A at 90 VAC and maximum load

Output Output power 65W

**DC output** 5V/9V/10V/12V/15V/20V **Hold-up time** 5ms at 115 Vac input

Output current limit <8.0A

Connector Non-Standard C6

Environmental Design Operating

temperature

32°F to 95°F (0° to 35°C)

Non-operating (storage)

**temperature** -4°F to 185°F (-20° to 85°C) **Altitude** 0 to 16,400 ft (0 to 5000m)

Humidity5% to 95%Storage Humidity5% to 95%

EMI and Safety Certifications \*CE Mark - full compliance with LVD and EMC directives

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

\* MTBF - over 100,000 hours at 25°C ambient condition.

AC Adapter 65 Watt Smart Dimensions (H x W x D) nPFC EM Barrel 4.5mm ......

New EM Weight

102 x 55 x 30 mm unit: 250q +/- 10q

**Input Efficiency** 88.0 % at 115 Vac and 89.0 % at 230 Vac

**Input frequency range** 47 ~ 63 Hz



### **Technical Specifications**

Input AC current Max. 1.7 A at 90 Vac

Output **Output power** 65W DC output 19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <11.0A

Connector **C6** 

**Environmental Design Operating** 

32°F to 95°F (0° to 35°C) temperature

Non-operating (storage)

temperature

-4°F to 185°F (-20° to 85°C)

88.0 % at 115 Vac and 89.0 % at 230Vac

Altitude 0 to 16.400 ft (0 to 5000m)

**Humidity** 20% to 95% **Storage Humidity** 10% to 95%

**EMI and Safety** Certifications

\*CE Mark - full compliance with LVD and EMC directives

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

\* MTBF - over 100.000 hours at 25°C ambient condition.

AC Adapter 65 Watt Smart Dimensions (H x W x D)

nPFC Standard Barrel 4.5mm Right Angle 1.8m

Weight

unit: 230g +/- 10g

90.0 x 51 x 28.5mm

Input **Input Efficiency** 

> Input frequency range 47 ~ 63 Hz

**Input AC current** Max. 1.7 A at 90 Vac

Output **Output power** 65W

> DC output 19.5V

Hold-up time 5ms at 115 Vac input

**Output current limit** <11.0A

Connector Non-Standard C6

**Environmental Design** Operating

32°F to 95°F (0° to 35°C) temperature

Non-operating (storage)

temperature

32°F to 95°F (0° to 35°C)

Altitude 0 to 16,400 ft (0 to 5000m)

**Humidity** 20% to 95% **Storage Humidity** 10% to 95%

**EMI and Safety** 

\*CE Mark - full compliance with LVD and EMC directives Certifications

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV: Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B.

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.



### **Technical Specifications**

\* MTBF - over 100,000 hours at 25°C ambient condition.

Battery SS 3 Cell 50 WHr

Long Life -PL

Dimensions (H x W x D)

L 278.7mm x W 76.3mm x H 7.1mm

Weight

193 +/- 10q

Cells/Type

**Temperature** 

3cell Lithium-Ion Polymer cell / P604883A1

Energy

Voltage

11.55V

**Amp-hour capacity** 

4.113Ah/ 4.330Ah

**Watt-hour capacity** 

50Wh

Operating (Charging)

0° to 50° C

Operating (Discharging)

-10° to 60° C

Warranty

based on system offering

**Optional Travel Battery** Available



### **Technical Specifications**

**Country of Origin** 

China



# Options and Accessories (Sold separately and availability may vary by country)

Туре	Description	Part Number
Cases	HP Essential Top Load Case (up to 15.6")	H2W17AA#xxx
	HP Slim Ultrabook Top Load	F3W15AA#xxx
	HP Basic/Essential Backpack	H1D24AA#xxx
	HP Exec Midnight 15.6" Backpack	1KM16AA#xxx
	·	
Docking	HP UltraSlim Docking Station	D9Y32AA#xxx
	HP UltraSlim Docking Station TAA US	E5C22AV#ABA
	HP Thunderbolt Dock 120W G2	2UK37AA
	HP Thunderbolt Dock 230W G2	2UK38AA
	HP TB Dock Audio Module	3AQ21AA
	HP TB Dock 120W G2 cable	3XB94AA
	HP TB Dock G2 combo cable	3XB96AA
	HP USB-C Universal Dock	1MK33AA#xxx
	HP Elite 90W Thunderbolt 3 Dock	1DT93AA#xxx
	HP USB-C Dock G4	3FF69AA#xxx
	HP USB-C Mini Dock	1PM64AA#xxx
	HP USB-C Travel Dock	T0K29AA#xxx
	HP USB Travel Dock	T0K30AA#xxx
	HP USB-C Universal Dock w/4.5mm Adapter	2UF95AA
	HP USB-C Universal Dock w/4.5mm Adapter - non-flash version	3DV65AA
	HP USB-C Dock G5	5TW10AA#XXX
	HP USB-C/A Universal Dock G2	5TW13AA#XXX
	HP Adjustable Dual Display Stand	AW664AA#xxx
	HP Display and Notebook Stand II	E8G00AA#xxx
	HP TB Dock G2 w/ Combo Cable	3TR87AA
	HP TB Dock 120W G2 w/ Audio	3YE87AA
Input/Output	HP Slim Wireless Keyboard and Mouse	T6L04AA#xxx
	HP Slim USB Keyboard and Mouse	T6T83AA#xxx
	HP Wireless (Link-5) Keyboard	T6U20AA#xxx
	HP USB Essential Keyboard and Mouse	H6L29AA#xxx
	HP Conferencing Keyboard	K8P74AA#xxx
	HP USB Collaboration Keyboard	Z9N38AA#xxx
	HP Wireless Collaboration Keyboard	Z9N39AA#xxx
	HP Comfort Grip Wireless Mouse	H2L63AA#xxx
	HP X4000b Bluetooth Mouse	H3T50AA#xxx
	HP 3-Button USB Laser Mouse	H4B81AA#xxx
	HP USB Travel Mouse	G1K28AA#xxx
	HP Ultra Mobile Wireless Mouse	H6F25AA#xxx
	HP Slim Bluetooth Mouse to AMO	F3J92AA#xxx
	HP Wireless Premium Mouse	1JR31AA#xxx
	HP USB Premium Mouse	1JR32AA#xxx



# Options and Accessories (Sold separately and availability may vary by country)

	HP Essential USB Mouse	2TX37AA#xxx
	HP Elite Presenter Mouse	2CE30AA#xxx
	HP USB-C to USB 3.0 Adapter	N2Z63AAA#xxx
	HP USB-C to USB-A Hub	Z6A00AA#xxx
	HP USB-C to DP	N9K78AA#xxx
	HP USB-C to VGA	N9K76AA#xxx
	HP HDMI to DVI	F5A28AA#xxx
	HP HDMI to VGA	H4F02AA#xxx
	HP USB-C to HDMI 2.0 Adapter	1WC36AA#xxx
Power	HP 65W Slim AC Adapter	H6Y82AA#xxx
	HP 90W Slim AC Adapter	H6Y83AA#xxx
	HP 90W Slim Combo AC Adapter w/ USB	H6Y84AA#xxx
	HP 45W Smart AC Adapter	H6Y88AA#xxx
	HP 65W Smart AC Adapter	H6Y89AA#xxx
	HP 90W Smart AC Adapter	H6Y90AA#xxx
	HP 45W 2-prong 4.5 mm DC jack AC Adapter	L6F60AA#ABJ
	HP 45W USB-C Power Adapter	1HE07AA#xxx
	HP 65W USB-C Power Adapter	1HE08AA#xxx
	65W USB-C Slim Power Adapter	3PN48AA
	HP Notebook Power Bank	N9F71AA#xxx
	HP USB-C Notebook Power Bank	1TZ86AA#xxx
	HP 45W USB-C Power Adapter	1HE07AA#xxx
	HP 65W USB-C Power Adapter	1HE08AA#xxx
UCC	HP Stereo 3.5mm Headset	T1A66AA#xxx
	HP Stereo USB Headset	T1A67AA#xxx
	HP UC Wireless Mono Headset	W3K08AA#xxx
	HP UC Wireless Duo Headset	W3K09AA#xxx
Storage	HP USB External DVDRW Drive	F2B56AA#xxx
	HP 256GB M2 PCIe NVME SSD TLC (2280)	1FU87AA#xxx
	HP 512GB M2 PCIe NVME SSD TLC 2280)	1FU88AA#xxx
Security	HP Docking Station Cable Lock	AU656AA#xxx
	HP Essential Combination Lock	TOY16AA#xxx
	HP Combination Lock	T0Y15AA#xxx
	HP Keyed Cable lock	T0Y14AA#xxx
	HP Keyed Cable Lock 10mm	T1A62AA#xxx
	HP Dual Head Keyed Cable Lock	T1A64AA#xxx
Displays	HP EliteDisplay E243d 23.8-inch Docking Monitor	1TJ76AA
	HP EliteDisplay E243 23.8-inch Monitor	1FH47AA



#### **HP EliteBook 830 G6 Notebook PC**

Options and Accessories (Sold separately and availability may vary by country)

HP EliteDisplay E273q 27-inch Monitor

1FH52AA



### **Change Log**

Date of change:	Version History:		Description of change:
May 28, 2019	From V1 to V2	Updated	Sure View Gen3
May 30, 2019	From V2 to V3	Updated	Lock Slot
June 7, 2019	From V3 to V4	Added	Environmental Section
June 10, 2019	From V4 to V5	Added	HP Cloud Recovery
July 2, 2019	From V5 to v6	Updated	Color Gamut

Copyright © 2019 HP Development Company, L.P. The only warranties for HP products are set forth in the express limited warranty

statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

Intel, Core, Thunderbolt and Intel vPro are trademarks or registered trademarks of Intel Corporation or its subsidiaries in the United States and other countries. SB Type-C™ and USB-C™ are trademarks of USB Implementers Forum. ENERGY STAR is a registered trademark of the U.S. Environmental Protection Agency. All other trademarks are the property of their respective owners.

